1.1 TO header

Application: TO (Transistor Outline) package is used as a base for mounting electronic and optical components such as semiconductors, laser diodes, and electronic circuits. It also provides electrical signals to the mounted components through lead pins.

Performance: It offers high airtightness, high insulation, good corrosion resistance, and wire bonding capability.

2.1 One pin and Two pins header

Application: Base for mounting electronic and optical components such as semiconductors, laser diodes, and electronic circuits.

Performance: In addition to ensuring conventional airtightness and insulation, our products also guarantee excellent dark current characteristics.

Low dark current
＜**0.04mA**

Tow-Pins

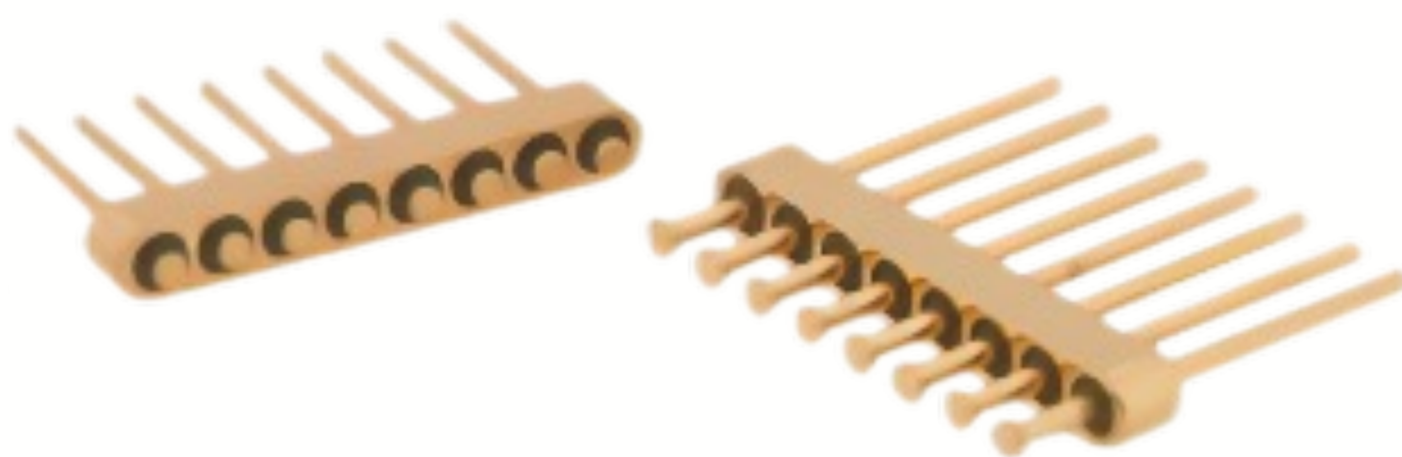
3.1 High-frequency connector

Applications: High-temperature sensors, batteries, capacitors, nuclear reactors, implantable medical devices, optoelectronic packaging, automotive safety airbags, and many other products and industries.

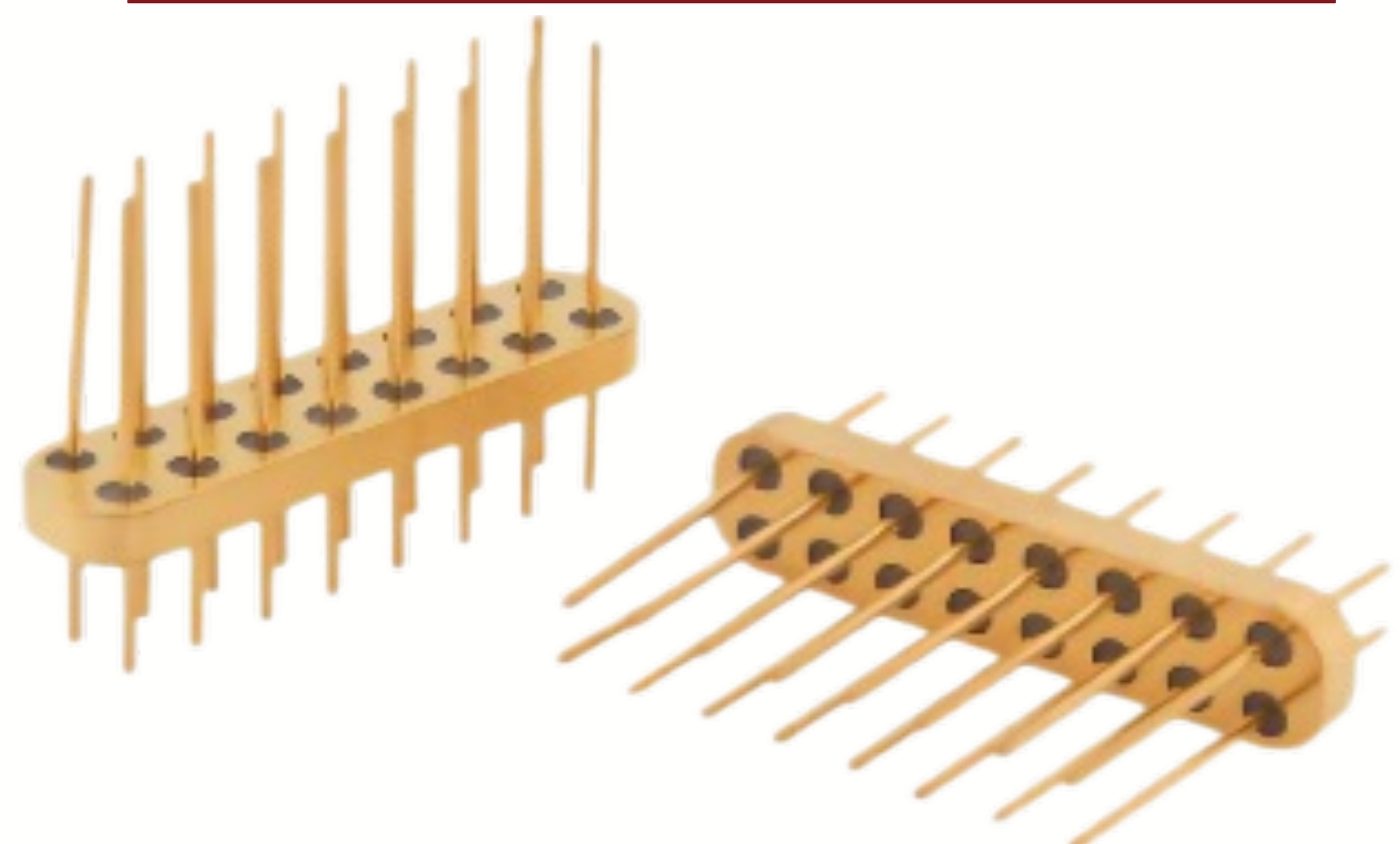
Performance: Glass packaging prevents moisture ingress or seal leaks, thereby preventing damage or malfunction of electrical components/systems or other substances within the package.

GPO/GPPO/G3PO

RF Insulator



Backplane connector



Multi-row connector

Cell: +1 (408) 8877187 Email: sophia@gem-oe.com
Add: 900E Hamilton, St 100, Campbell, CA 95008 http://www.gem-optics.com

4.1 High-energy hybrid tantalum capacitor casing

Applications: communication, computing, aerospace, aviation, national defense, and military industries

Ageing test	≥2000hrs
Glass Color	Black or Brown
Voltage-endurance	≥1000VDC； ≥600VAC
Leak Rate	≤1.013×10-8Pa- m3 / s
Insulation Resistance	≥1×108Ω(500VDC)
Operating temperature	-55℃`+125℃

5.1 Metal Package

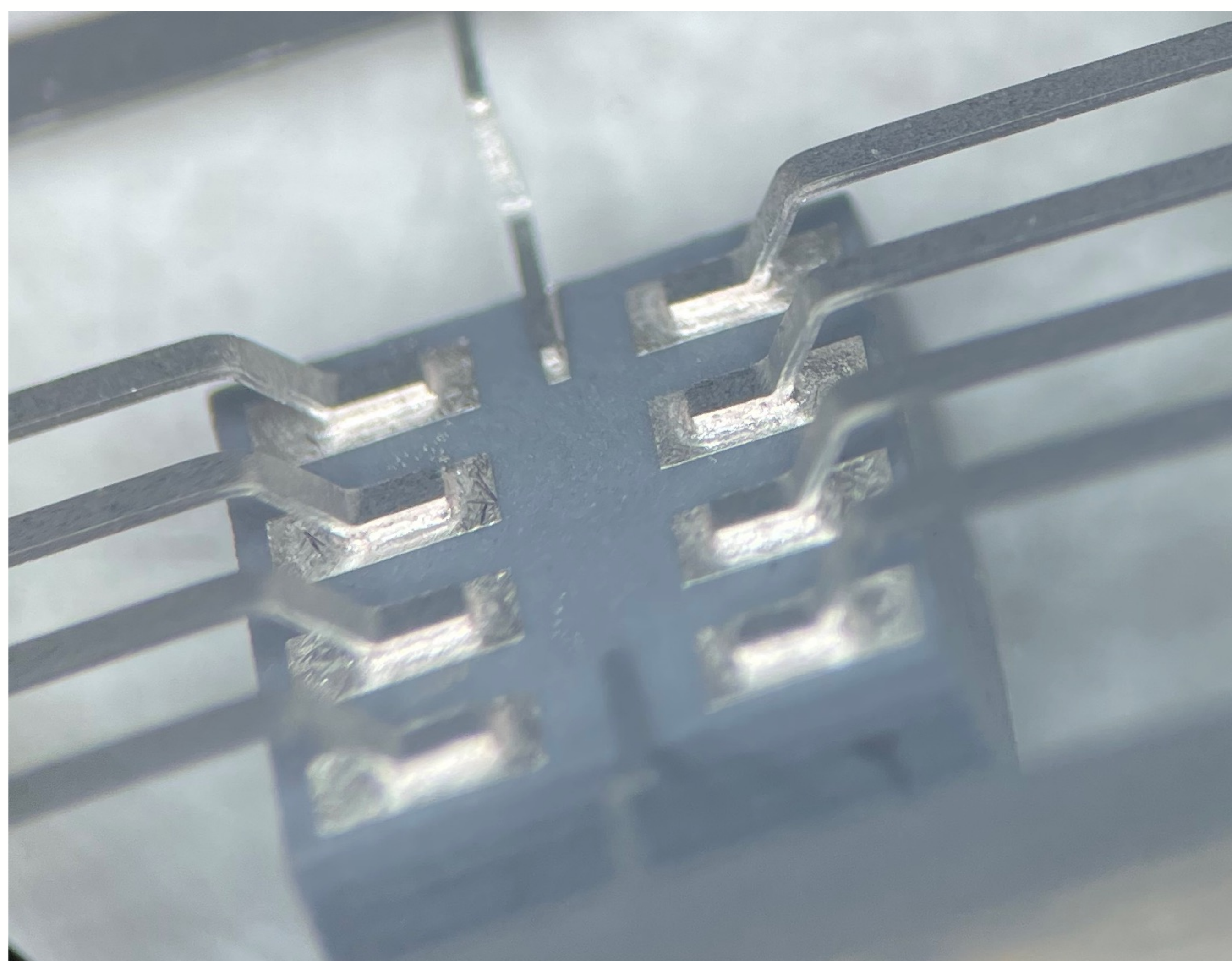
Applications: Used in DC/DC converters, EMI filters, hybrid integrated circuits, lasers, microwave transmission, and other fields.

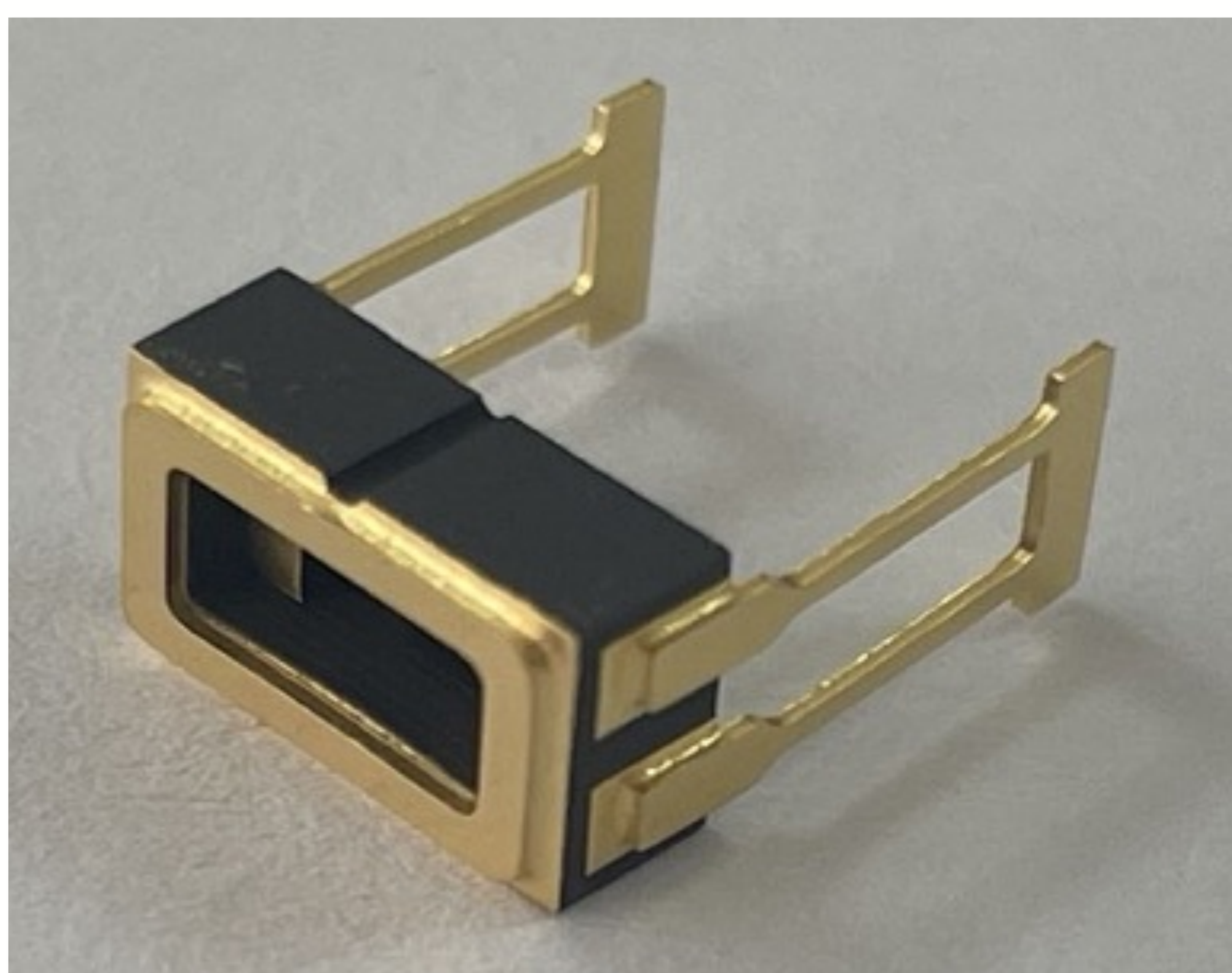
Performance: The product's outer structure is typically in the form of dual in-line and flat metal shell, fully sealed. It features a wide operating temperature range, small size, lightweight, and high reliability.

6.1 Ceramic DIP packaging

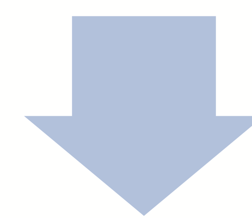
Applications: Insulated Gate (MOSFET), operational amplifiers, chip amplifiers, transceiver chips, memory chips, rectifier bridges, etc.

Performance: High soldering strength, high airtightness, high insulation, and a good appearance of the electroplating layer.

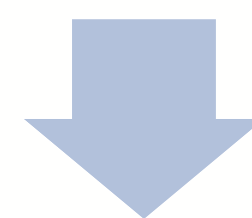




Nickel-plated casing



Lead and ring frame welding



Electroplated nickel / gold